	CONNECTING CS INDUSTRIES® International and Pan-	C, Bannockb	ourn, Illinois. A	All rights reserved untions.	nder both	This docume level parts, t	ent is a declarat he declaration	tion of th encompa	e substances asses all lowe	within the er level mat	manufactur erials for wh	er listed ite nich the ma	m. Note: if nufacturer	the item is an as has engineering	sembly with lowe responsibility.	
1752-21.1					Form Type Distribute	* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					eous Materia	als and Mfg Information				
Supplier	r Information															
Company	name*	Company un	Company unique ID			Unique ID Authority					Response Date*					
nsemi												2024-05-10				
Contact N	lame		Title - Contact			]	Phone - Contact*				Email - Contact*					
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
uthorize	ed Representative*		Title - Representative			]	Phone - Representative*				Email - Representative*					
Product-I	Env-Stewards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number Mfr Item		n Number Mfr Item Name				Effective Date	Version Manufacturing Site		ing Site	W	'eight*	UOM	Unit Type		
		FSQ0765RQWDTU 650		650V QR Cntrlr w/swtch		2024-05-10		РВВ		22	239.009	mg	Each			
/lanufa	cturing Proccess Informat	ion														
	Terminal Plating / Grid Array Material		Terminal Base Alloy J-STD-020		J-STD-020 MS	L Rating	Peak Process Body Temperat		ure Max Time at Peak Tem		Temperatu	re Numbe	er of Reflow Cyc	eles		
Matte Tin (Sn) - annealed		C	CU Alloy NA			0 C		С	30		second	s <b>3</b>				
omments	3															
or more	information regarding material of	composition	please refer to	page 3												

RoHS Material Composition Declaration				Declaration Type *	Detailed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et							
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of						
RoHS Declaration * 4 - Item(	s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted						
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.											
Supplier Digital Signature	astislav Drska	Le									

## Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	9.8	mg	Supplier	Silicon (Si)	7440-21-3		9.8	mg
Die Attach Epoxy	0.254	mg	Supplier	Poly(oxypropylene)diamine	9046-10-0		0.0076	mg
			Supplier	Silver (Ag)	7440-22-4		0.2159	mg
			Supplier	Proprietary	Proprietary Data		0.0127	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.0178	mg
vie Attach Solder	3.061	mg	Supplier	Silver (Ag)	7440-22-4		0.0765	mg
			А	Lead (Pb)	7439-92-1	7a	2.8314	mg
			Supplier	Tin (Sn)	7440-31-5		0.1531	mg
lead Frame	1264.59	mg	Supplier	Silver (Ag)	7440-22-4		2.91	mg
			Supplier	Tin (Sn)	7440-31-5		1.55	mg
			Supplier	Copper (Cu)	7440-50-8		1260.0045	mg
			Supplier	Phosphorus (P)	7723-14-0		0.1255	mg
Iold Compound-Black	950.0	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		114	mg
			Supplier	Carbon Black (C)	1333-86-4		4.75	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		831.25	mg
Plating	11.0	mg	Supplier	Tin (Sn)	7440-31-5		11	mg
Wire Bond - Cu	0.304	mg	Supplier	Copper (Cu)	7440-50-8		0.304	mg